



EFW

503.43552X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SHIBATA et al

Serial No.: 10/797,003

Filed: March 11, 2004

For: Mold Die And Method For Manufacturing Semiconductor
Device Using The Same

Art Unit: 2814

Examiner: Chambliss, A.

AMENDMENT

Mail Stop: Amendment
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

December 21, 2005

Sir:

This is in response to the Office Action mailed September 22, 2005, in connection with the above-identified application. The amendments are listed below and set forth on the following pages.

Amendments to the Title;

Amendment to the Specification;

Amendments to the Claims;

Amendments to the Drawings; and

Remarks are included following the amendments.

Amendments to the Title:

Please amend the title as follows:

~~Mold Die And Method For Manufacturing A Semiconductor Device Using The Same~~